

## IN THE CLAIMS

Per the revised amendment practice, a complete listing of all claims in the application follows.

Claims 1-6 (cancelled).

7. (Currently amended) A method of stacking a plurality of die, comprising mounting an upper die on a lower die; ~~and~~ defining ~~a minimum~~ an angular offset with said mounting, wherein said ~~minimum~~ angular offset allows access to a bonding site on said lower die, and wherein at least one end of said upper die is unsupported.
8. (Previously presented) The method in claim 7, further comprising a step of mounting a lowest die on a substrate.
9. (Currently amended) A method of manufacturing a multichip module including dies, comprising:  
stacking ~~all of~~ said dies in a manner such that corresponding portions of any two of said dies define respective axes, and wherein said axes define an offset angle;  
~~bonding wire to said dies; and~~  
~~ensuring that said step of stacking all of said dies occurs with no intervening bonding step~~  
refraining from propping at least one of said dies in a region extending laterally from any underlying die.
10. (Currently amended) A method of manufacturing a multichip module including dies, comprising:  
stacking ~~all of~~ said dies, wherein corresponding portions of any two of said dies define respective axes, and wherein said axes define an offset angle; and  
~~bonding wire to said dies;~~

~~wherein said step of stacking comprises stacking all of said dies before said step of~~  
~~bonding wire to said dies~~  
allowing at least one end of at least one of said dies to be free of support.

11. (Currently amended) A method of manufacturing a multichip module including dies,  
comprising:

stacking ~~all of~~ said dies, wherein corresponding portions of any two of said dies define  
respective axes, and wherein said axes define an offset angle; and

~~bonding wire to said dies;~~

~~wherein said step of bonding comprises bonding all of said wire only after said~~  
~~step of stacking all of said dies~~

limiting direct support for a first die of said dies to a region between said first die and a  
second die of said dies, said second die immediately underlying said first die.

12. (Currently amended) A method of assembling a plurality of dies, comprising:

stacking said plurality of dies along an axis;

establishing an orientation for each die of said plurality of dies;

~~marginally~~ clearing a line of sight to contact areas of any immediately underlying die  
with said orientation for said each die, wherein said line of sight is parallel to said  
axis; and

clearing a line of sight to contact areas of any underlying die with said orientation for  
said each die; and

directly holding up at least one of said plurality of dies only in a region that intersects  
said axis.

13. (Currently amended) A method of stacking a plurality of chips

spiraling said plurality of chips around an axis perpendicular to said plurality of chips;  
and

ensuring ~~at most a minimum~~ bond pad clearance to each chip of said plurality of chips;  
and

limiting reinforcement of at least one of said plurality of chips to regions intersecting said axis.

14. (Previously presented) The method in claim 13, wherein said step of spiraling said plurality of chips around an axis further comprises spiraling said plurality of chips around an axis passing through said each chip.

15. (Previously presented) The method in claim 14, wherein said step of spiraling said plurality of chips around an axis further comprises spiraling said plurality of chips around an axis passing through a center of said each chip.

16. (Previously presented) The method in claim 15, wherein said ensuring step comprises rotating a chip around said axis at least to an extent that a bond pad on an underlying chip is exposed.

17. (Currently amended) A method of arranging ~~a~~ dies in a multichip device, comprising:  
serially stacking said ~~a~~ dies; and  
establishing a unique orientation for each die of said ~~a~~ dies, wherein said orientation for said each die defines ~~less than a maximum~~ an underlying bond pad clearance,  
and wherein at least one orientation leaves at least one end of at least one of said dies free of bolstering.